

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L1 | 2000 | (semiconductor or wafer) same chuck same (tape or pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/11 13:47 |
| L2 | 939 | 1 and (polish\$3 or grind\$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/11 13:35 |
| L3 | 1932 | (semiconductor or wafer) same (\$4holder) same (tape or pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/11 13:28 |
| L4 | 1172 | 3 and (polish\$ or grind\$3) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/11 13:28 |
| L6 | 68 | 2 and cleaning and drying | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/11 13:35 |
| L7 | 112 | (semiconductor or wafer) same chuck same (mesh) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/11 13:55 |